

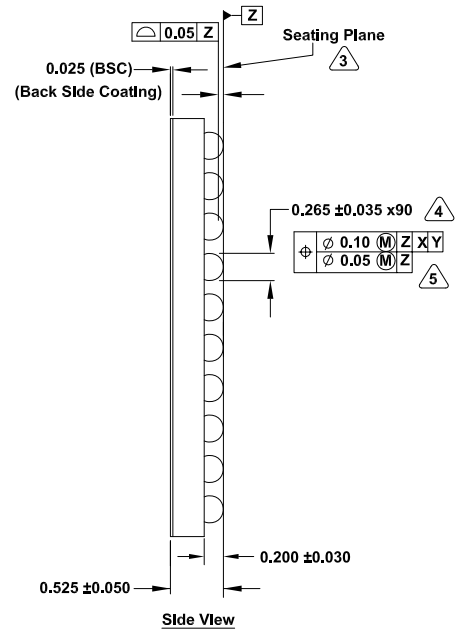
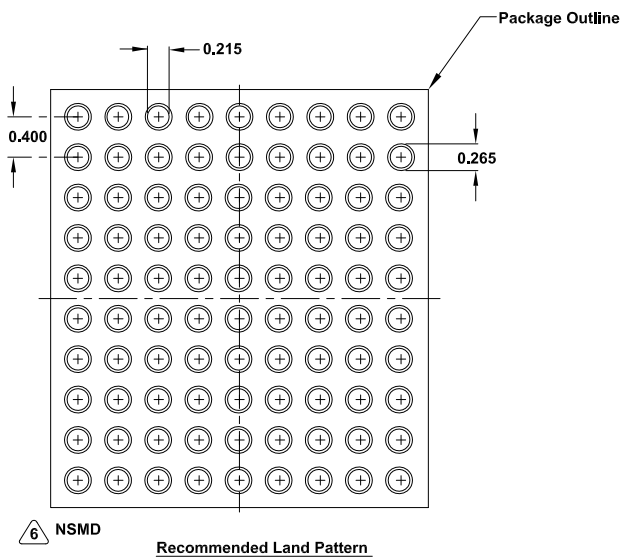
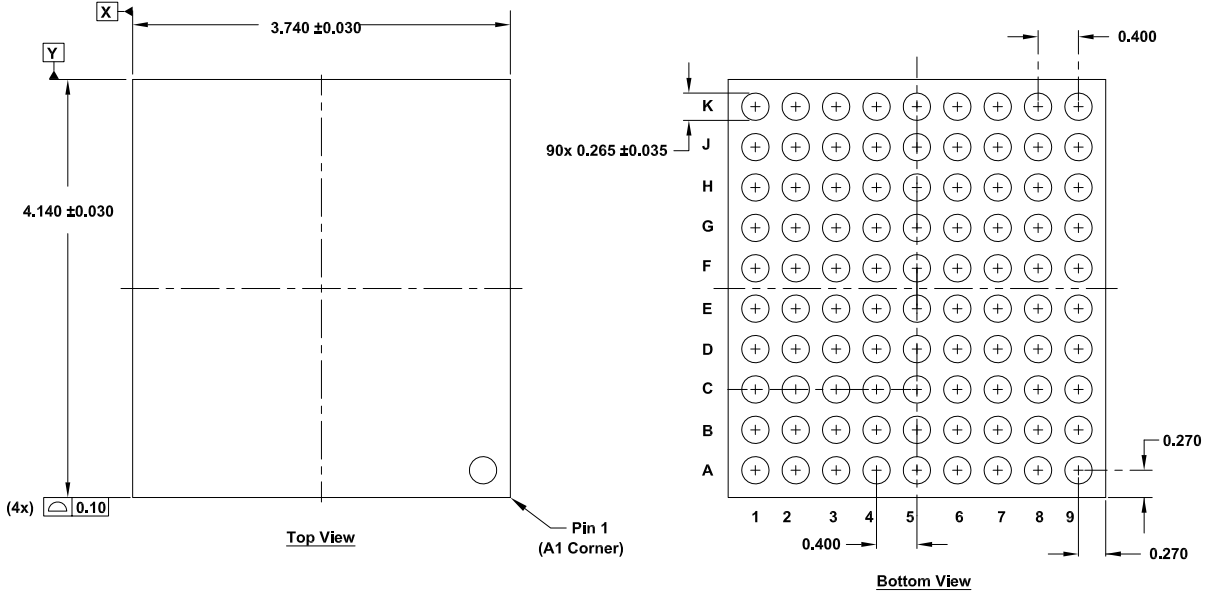
# Plastic Packages for Integrated Circuits

## Package Outline Drawing

W9x10.90

9x10 Array 90 Balls Wafer Level Chip Scale Package (with 25um BSC)

Rev 1, 2/2021



### NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerances per ASME Y14.5-1994.
- ③. Primary datum  $Z$  and seating plane are defined by the spherical crowns of the bump.
- ④. Dimension is measured at the maximum bump diameter parallel to primary datum  $Z$ .
- ⑤. Bump position designation per JESD 95-1, SPP-010.
- ⑥. NSMD refers to non-solder mask defined pad design per TB451.